IN THE SPECIFICATION:

Please replace the paragraph from page 9, line 25, to page 10, line 10, with the following paragraph:

The diffuser plate 44 provides support for the permeable disc 28 in the partial enclosure 34. The diffuser plate 44 can be secured in the partial enclosure 34 using fasteners such as screws 48 or other means such as snap or interference fit with the enclosure, being suspended therein and the like. The diffuser plate 44 can be made of a material such as a plastic, e.g., fluoropolymer, PE, TEFLON®, PFA, PES, HDPE, UHMW or the like. The diffuser plate 44, in at least one embodiment, includes a plurality of holes or channels 46 formed therein. The holes 46 are sized to enable fluid flow therethrough and to provide uniform distribution of electrolyte through the permeable disc 28 to the substrate 22. The permeable disc 28 can be fastened to the diffuser plate 44 using adhesives that are compatible with the fluid environment and the processing requirements. The diffuser plate 44 is preferably spaced from the anode 26 to provide a wider process window, thus reducing the sensitivity of plating film thickness to the anode dimensions, and to separate the accelerator and suppressor decomposition by-products, for example, a mono-sulfide compound degraded from an accelerator, such as bis(3-sulfopropyl) disulfide, $C_6H_{12}Na_2O_6S_4$, commercially available from the Raschig Corp. of Germany, from a main plating volume 38 as shown in Figure 2.

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Please replace the paragraph at page 13, lines 8-23, with the following paragraph:

Figures 5A, 5B, 5C and 5D depict the substrate 22 being loaded into the carrier assembly 30. In Fig. 5A, the gripper fingers 74 are rotated to form the seat 50 that receives the substrate 22 from the robot not shown. The head assembly 78 is disposed in a first position 502 proximate the seat assembly 76. The substrate clamps 322 are fully extended from the first side 314 of the support plate 306. After the robot is removed leaving the substrate 22 in the seat 50 of the gripper finger 74, the head assembly 78 is then extended into a second position 504 to load the substrate 22 held in the seat 50 between the substrate clamps 322 (See Figure 5B). The first clamps 402

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center the substrate 22 relative to the head assembly 78. The clamps 322 are then retracted towards the support plate 306. The angled wall 422 of the second clamp 404 contacts the beveled edge of the substrate 22 and pulls the substrate 22 against the support plate 306. The interaction between the angled wall 422 and substrate 22 additionally causes the second clamp 404 to flex outwardly against the détente pin 416, displacing the bottom surface 420 of the notch 418 from the substrate perimeter. The flexed second clamp 404 and the détente pin 416 combine to urge the second clamp 404 inwardly to capture the substrate 22 against the support plate 306 while providing good electrical contact between the clamp 404 and substrate 22 (See Figures 5C and 5D).

Please replace the paragraph at page 15, lines 13-22, with the following paragraphs:

The apparatus 800 discloses an enclosure 834 which typically includes a diffuser plate 844 and a permeable disc 828 disposed therein in a first relative position 810 adjacent to but vertically displaced from substrate 822 disposed in carrier assembly 830 described above in Figure 2. The permeable disc 828, such as a polishing pad, is disposed and supported in the electrolyte cell on the diffuser plate 844. The partial enclosure 834 can be a bowl shaped member made of a plastic such as fluoropolymers, TEFLON®, PFA, PE, PES, or other materials that are compatible with plating chemistries. The enclosure 834 generally defines a container or electrolyte cell in which an electrolyte or other polishing/deposition fluid can be confined. The electrolyte used in processing the substrate 22 can include metals such as copper, nickel or other materials which can be electroless deposited onto a substrate.

Please replace the two paragraphs at page 18, lines 8-22, with the following paragraphs:

Fig. 11 depicts a sectional view of the substrate carrier head assembly 1004 supported above the plating station 1002. In one embodiment, the substrate carrier head assembly 1004 is substantially similar to the substrate carrier assembly 30 described above. Similarly, the plating station 1002 includes a partial enclosure 1102